

07-22-2003

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TO THE ASSISTANT COMMISSIONER FOR

102504429

documents or copy thereof

1. Name of conveying party(ies): (If multiple assignors, list numerically)

- 1. Nobuo Matsuki
- 2. Yoshinori Morisada
- 3. Yasuyoshi Hyodo
- 4. Seijiro Umemoto

7-17-03

2. Name and address of receiving party(ies)

**Name:** ASM JAPAN K.K.  
**Address:** 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan

Additional name(s) of conveying party(ies) attached?  
 ( ) Yes (X) No

Additional name(s) of receiving party(ies) attached?  
 ( ) Yes (X) No

OFFICE OF THE ASSISTANT COMMISSIONER FOR PATENT AND TRADEMARK RECORDATION  
 FINANCIAL SERVICES SECTION  
 JUL 17 11 17 AM '03

3. Nature of conveyance:

- Assignment
- Merger
- Security Agreement
- Change of Name
- Other:

Execution Date: (If multiple assignors, list execution dates in numerical order corresponding to numbers indicated in 1 above) 1. 04/23/03 2. 04/23/03 3. 04/24/03 4. 04/23/03

4. Application number(s) or Patent number(s):

- Application(s) filed herewith Execution Date(s):
- Patent Application No.: 10/402,109  
Filing Date: March 27, 2003
- Patent No.:  
Issuc Date:

Additional numbers attached? ( ) Yes (X) No

5. Name and address of party to whom correspondence concerning document should be mailed:

**Name:** Gordon H. Olson  
 KNOBBE, MARTENS, OLSON & BEAR, LLP  
**Customer No.** 20,995  
**Internal Address:** Fourteenth Floor  
**Street Address:** 2040 Main Street  
 City: Irvine State: CA ZIP: 92614  
**Attorney's Docket No.:** ASMJP.25CP5PPP

7. Total fee (37 CFR 1.21(h)): \$40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number: 11-1410

Please charge this account for any additional fees which may be required, or credit any overpayment to this account.

6. Total number of applications and patents involved: 1

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document.

Katsuhiro Arai  
 Name of Person Signing

*Katsuhiro Arai*  
 Signature

July 16, 2003  
 Date

43,315  
 Registration No.

Total number of pages including cover sheet, attachments and document: 3

Mail documents to be recorded with required cover sheet information to:

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 Alexandria, VA 22313-1450

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## ASSIGNMENT

WHEREAS, We, Nobuo Matsuki, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, Yoshinori Morisada, a Japanese, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, Yasuyoshi Hyodo, a Japanese, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, and Seijiro Umemoto, a Japanese, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, , have invented certain new and useful improvements in a INSULATION FILM ON SEMICONDUCTOR SUBSTRATE AND METHOD FOR FORMING SAME which we have filed an application for Letters Patent in the United States, on March 27, 2003 as Application Serial No. 10/402,109.

AND WHEREAS, ASM JAPAN K. K.(hereinafter "ASSIGNEE"), a Japan Corporation, with its principal place of business at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

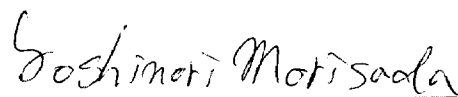
AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

This 23 day of April, 2003



Nobuo Matsuki

This 23 day of April, 2003



Yoshinori Morisada

Witness

This 24 day of April, 2003

兵頭 靖行  
Yasuyoshi Hyodo

This 23 day of April, 2003

梅本 浄二郎  
Seijiro Umemoto

Witness

木村 靖行